

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): VANDENTOP et al.	Confirmation No.: 9242
Application No.: 10/667,694	Attorney Docket No.: P16922
Filed: September 22, 2003	Group Art Unit: 2841
Title: INTEGRATED CIRCUIT DIE/PACKAGE INTERCONNECT	Examiner: Tuan T. Dinh
	PTO Customer Number 28062

Mail Stop Issue Fee (via EFS)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL LETTER

Sir:

Applicants hereby submit the following document(s) for the above-identified patent application:

1. Part B – Fee Transmittal.
2. Credit Card Authorization Payment form for \$1740.

Respectfully submitted,

December 14, 2007
Date

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